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PRODUCT INFORMATION NOTIFICATION

Subject: V_{DD} Power-Down Ramp Rate (t_{VF}) Specification Change in the Datasheet for Select

F-RAM Devices

To: TOKYO ELECTRON DEVICE

TELDEVICE

cy-inside@teldevice.co.jp

Change Type: Minor

Description of Change:

Cypress announces a V_{DD} power-down ramp rate (t_{VF}) specification change for 16Kb, 4.5-5.5 V, I2C F-RAM. The t_{VF} specification (guaranteed-by-design, not a production tested spec) will be changed from 3.3 μ s/V to 30 μ s/V in the datasheet. The purpose of this change is to standardize the t_{VF} spec across the serial F-RAM product family. There is no change to silicon design, test methodology or manufacturing sites, and hence we expect end applications to be unaffected.

The updated product datasheet is attached to this notification.

Part Numbers Affected: 2

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change.

Approximate Implementation Date:

This change will be effective with the date of this notification.

Anticipated Impact:

There is no change to the product. Products manufactured with revised datasheet parameter are completely compatible with existing product from fit, form, functional, parametric, and quality performance perspectives.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative contact the PCN Administrator at pcn_adm@cypress.com .	or
Sincerely,	
Cypress PCN Administration	